

TC74HC175AP, TC74HC175AF, TC74HC175AFN

QUAD D-TYPE FLIP FLOP WITH CLEAR

The TC74HC175A is a high speed CMOS D-TYPE FLIP FLOP fabricated with silicon gate C²MOS technology.

It achieves the high speed operation similar to equivalent LSTTL while maintaining the CMOS low power dissipation.

Information signals applied to D inputs are transferred to the Q and $\bar{Q}$ outputs on the positive going edge of the clock pulse.

When the $\overline{\text{CLR}}$ input is held low, the Q outputs are at the low logic level and the $\bar{Q}$ outputs are at the high logic level independent of the other inputs.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

FEATURES:

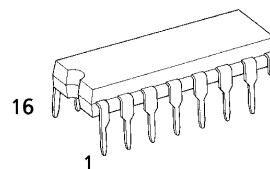
- High Speed..... $f_{\text{MAX}} = 63\text{MHz}(\text{typ.})$
at $V_{\text{CC}} = 5\text{V}$
- Low Power Dissipation..... $I_{\text{CC}} = 4\mu\text{A}(\text{Max.})$ at $T_a = 25^\circ\text{C}$
- High Noise Immunity..... $V_{\text{NIH}} = V_{\text{NIL}} = 28\% V_{\text{CC}}(\text{Min.})$
- Symmetrical Output Impedance... $|I_{\text{OH}}| = I_{\text{OL}} = 4\text{mA}(\text{Min.})$
- Balanced Propagation Delays..... $t_{\text{PLH}} \approx t_{\text{PHL}}$
- Wide Operating Voltage Range... $V_{\text{CC}}(\text{opr.}) = 2\text{V} \sim 6\text{V}$
- Pin and Function Compatible with 74LS175

TRUTH TABLE

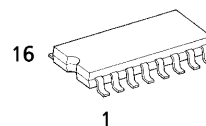
INPUTS			OUTPUTS		FUNCTION
$\overline{\text{CLR}}$	D	CK	Q	$\bar{Q}$	
L	X	X	L	H	Clear
H	L	$\downarrow$	L	H	—
H	H	$\downarrow$	H	L	—
H	X	$\downarrow$	Q_n	$\bar{Q}_n$	No change

X : Don't Care

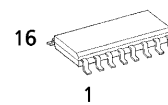
(Note) The JEDEC SOP (FN) is not available in Japan.



P (DIP16-P-300-2.54A)
Weight : 1.00g (Typ.)

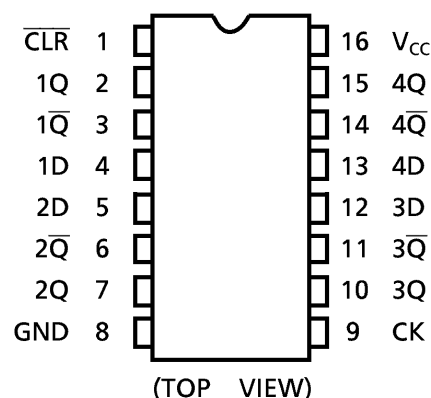


F (SOP16-P-300-1.27)
Weight : 0.18g (Typ.)

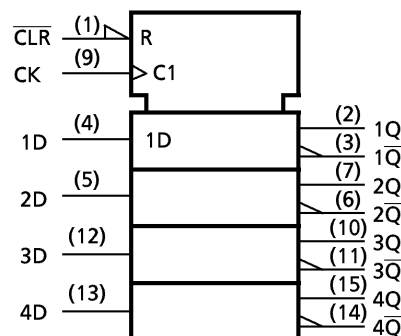


FN (SOL16-P-150-1.27)
Weight : 0.13g (Typ.)

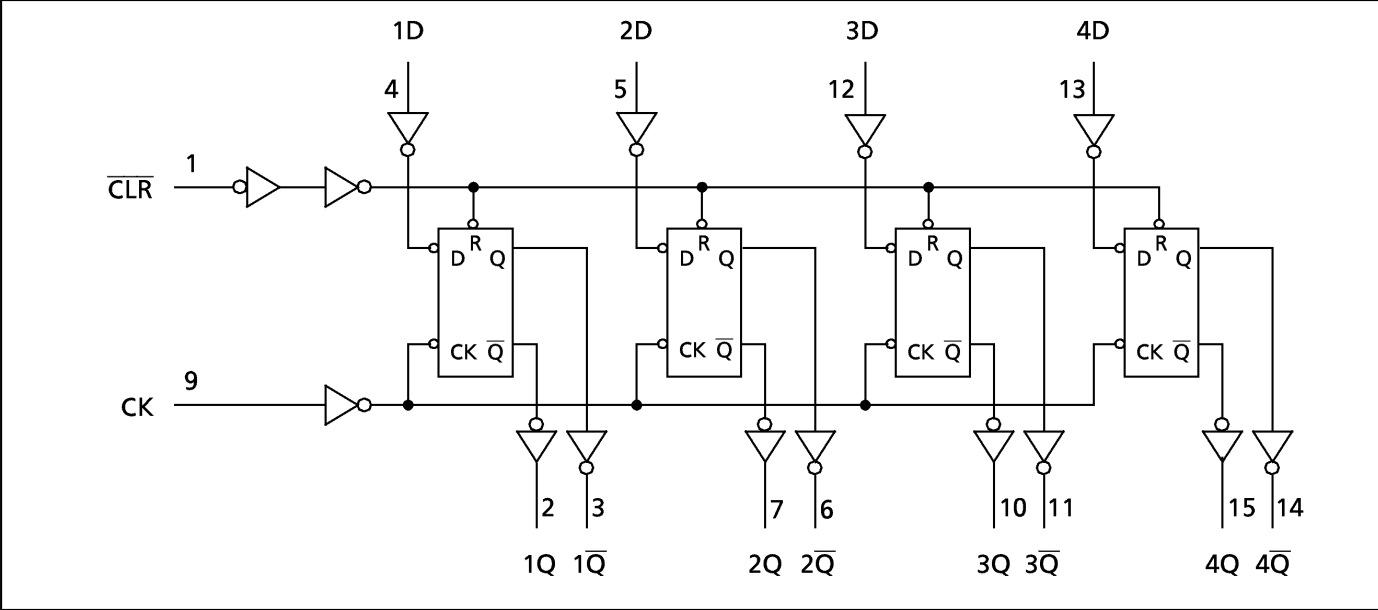
PIN ASSIGNMENT



IEC LOGIC SYMBOL



SYSTEM DIAGRAM



ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	V_{CC}	$-0.5 \sim 7$	V
DC Input Voltage	V_{IN}	$-0.5 \sim V_{CC} + 0.5$	V
DC Output Voltage	V_{OUT}	$-0.5 \sim V_{CC} + 0.5$	V
Input Diode Current	I_{IK}	± 20	mA
Output Diode Current	I_{OK}	± 20	mA
DC Output Current	I_{OUT}	± 25	mA
DC V_{CC} /Ground Current	I_{CC}	± 50	mA
Power Dissipation	P_D	500 (DIP)* / 180 (SOP)	mW
Storage Temperature	T_{stg}	$-65 \sim 150$	$^{\circ}C$

*500mW in the range of $T_a = -40^{\circ}C \sim 65^{\circ}C$. From $T_a = 65^{\circ}C$ to $85^{\circ}C$ a derating factor of $-10mW/^{\circ}C$ shall be applied until 300mW.

RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	V_{CC}	2 ~ 6	V
Input Voltage	V_{IN}	0 ~ V_{CC}	V
Output Voltage	V_{OUT}	0 ~ V_{CC}	V
Operating Temperature	T_{opr}	$-40 \sim 85$	$^{\circ}C$
Input Rise and Fall Time	t_r, t_f	0 ~ 1000 ($V_{CC} = 2.0V$) 0 ~ 500 ($V_{CC} = 4.5V$) 0 ~ 400 ($V_{CC} = 6.0V$)	ns

DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	V _{CC} (V)	Ta = 25°C			Ta = -40~85°C		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	
High - Level Input Voltage	V _{IH}		2.0 4.5 6.0	1.50 3.15 4.20	— — —	— — —	1.50 3.15 4.20	— — —	V
Low - Level Input Voltage	V _{IL}		2.0 4.5 6.0	— — —	— — —	0.50 1.35 1.80	— — —	0.50 1.35 1.80	V
High - Level Output Voltage	V _{OH}	V _{IN} = V _{IH} or V _{IL}	I _{OH} = -20 μA 4.5 6.0	2.0 4.4 5.9	2.0 4.5 6.0	— — —	1.9 4.4 5.9	— — —	V
				4.5 6.0	4.18 5.68	4.31 5.80	— —	4.13 5.63	
Low - Level Output Voltage	V _{OL}	V _{IN} = V _{IH} or V _{IL}	I _{OL} = 20 μA 4.5 6.0	2.0 — —	0.0 0.0 0.0	0.1 0.1 0.1	— — —	0.1 0.1 0.1	V
				4.5 6.0	— —	0.17 0.18	0.26 0.26	— —	
Input Leakage Current	I _{IN}	V _{IN} = V _{CC} or GND	6.0	—	—	±0.1	—	±1.0	μA
Quiescent Supply Current	I _{CC}	V _{IN} = V _{CC} or GND	6.0	—	—	4.0	—	40.0	

TIMING REQUIREMENTS (Input t_r = t_f = 6ns)

PARAMETER	SYMBOL	TEST CONDITION	V _{CC} (V)	Ta = 25°C		Ta = -40~85°C	UNIT
				TYP.	LIMIT	LIMIT	
Minimum Pulse Width (CK)	t _{W(L)} t _{W(H)}		2.0	—	75	95	ns
			4.5	—	15	19	
			6.0	—	13	16	
Minimum Pulse Width (CLR)	t _{W(L)}		2.0	—	75	95	
			4.5	—	15	19	
			6.0	—	13	16	
Minimum Set-up Time	t _s		2.0	—	75	95	
			4.5	—	15	19	
			6.0	—	13	16	
Minimum Hold Time	t _h		2.0	—	0	0	
			4.5	—	0	0	
			6.0	—	0	0	
Minimum Removal Time	t _{rem}		2.0	—	75	95	
			4.5	—	15	19	
			6.0	—	13	16	
Clock Frequency	f		2.0	—	6	5	MHz
			4.5	—	31	25	
			6.0	—	36	29	

AC ELECTRICAL CHARACTERISTICS ($C_L = 15\text{pF}$, $V_{CC} = 5\text{V}$, $T_a = 25^\circ\text{C}$, Input $t_r = t_f = 6\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Output Transition Time	t_{TLH} t_{THL}		—	4	8	ns
Propagation Delay Time ($CK - Q$, $\bar{Q}$)	t_{pLH} t_{pHL}		—	16	24	
Propagation Delay Time ($CLR - Q$, $\bar{Q}$)	t_{pLH} t_{pHL}		—	13	21	
Maximum Clock Frequency	f_{MAX}		36	63	—	MHz

AC ELECTRICAL CHARACTERISTICS ($C_L = 50\text{pF}$, Input $t_r = t_f = 6\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION	Ta = 25°C				Ta = -40~85°C		UNIT
			V _{CC} (V)	MIN.	TYP.	MAX.	MIN.	MAX.	
Output Transition Time	t _{TLH}		2.0	—	30	75	—	95	ns
	t _{THL}		4.5	—	8	15	—	19	
				6.0	—	7	13	—	
Propagation Delay Time (CK—Q, $\overline{Q}$)	t _{PLH}		2.0	—	70	140	—	175	
	t _{PHL}		4.5	—	19	28	—	35	
				6.0	—	16	24	—	
Propagation Delay Time (CLR—Q, $\overline{Q}$)	t _{PLH}		2.0	—	50	125	—	160	
	t _{PHL}		4.5	—	16	25	—	32	
				6.0	—	12	22	—	27
Maximum Clock Frequency	f _{MAX}		2.0	6	14	—	5	—	MHz
			4.5	31	53	—	25	—	
			6.0	36	63	—	29	—	
Input Capacitance	C _{IN}			—	5	10	—	10	pF
Power Dissipation Capacitance	C _{PD} (1)			—	53	—	—	—	

Note (1) C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation :

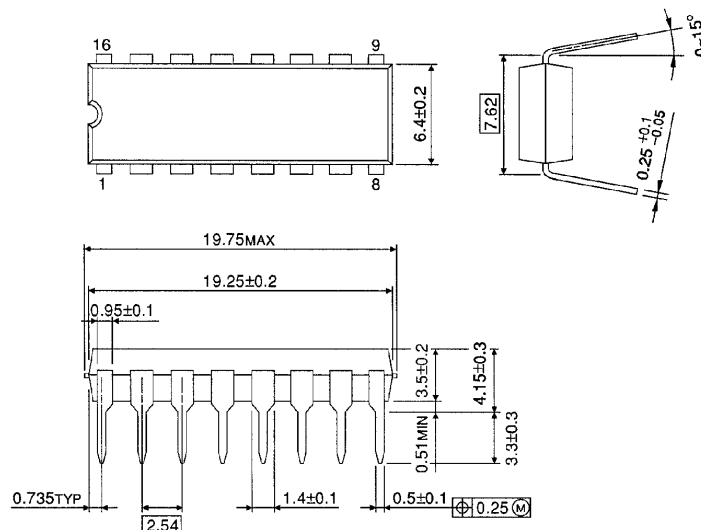
$$I_{CC}(\text{opr}) = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC} / 4 \text{ (per F / F)}$$

And the total C_{PD} when n pcs. of Flip Flop operate can be gained by the following equation :

$$CPD(\text{total}) = 32 + 21 \cdot n$$

DIP 16PIN PACKAGE DIMENSIONS (DIP16-P-300-2.54A)

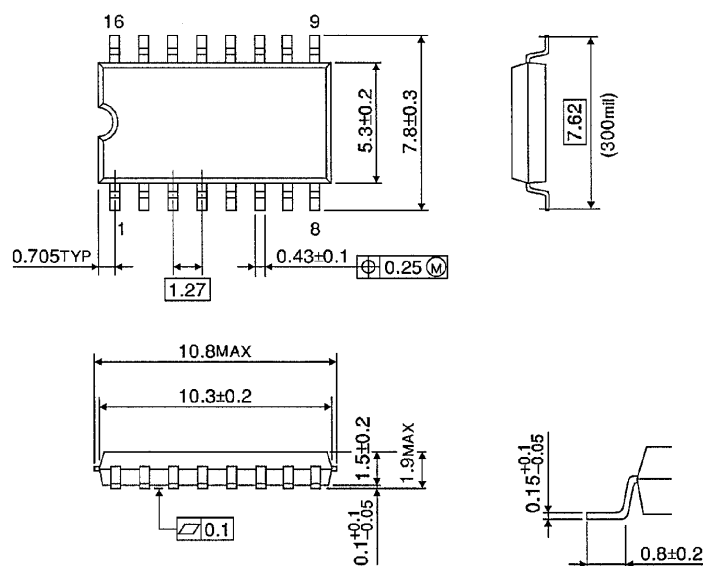
Unit in mm



Weight : 1.00g (Typ.)

SOP 16PIN (200mil BODY) PACKAGE DIMENSIONS (SOP16-P-300-1.27)

Unit in mm

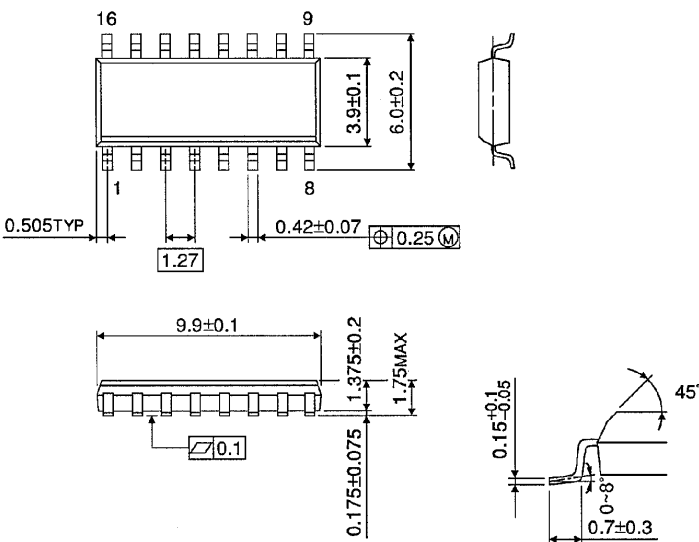


Weight : 0.18g (Typ.)

SOP 16PIN (150mil BODY) PACKAGE DIMENSIONS (SOL16-P-150 -1.27)

Unit in mm

(Note) This package is not available in Japan.



Weight : 0.13g (Typ.)

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000707EBA

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